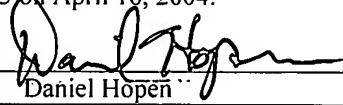


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Talieh et al. Serial No.: Not yet assigned Filed: April 16, 2004 Title: Device Providing Electrical Contact To The Surface Of A Semiconductor Workpiece During Processing	Group Art Unit: Not yet assigned Examiner: Not yet assigned Docket: NT-105C5-US CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the US Postal Service as Express Mail with mailing label <u>ER619641183US</u> Post Office to Addressee in a postage-paid envelope addressed to the Commissioner for Patents, P.O. BOX 1450, Alexandria, VA 22313 on April 16, 2004. Signed:  Daniel Hopen
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INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. BOX 1450
Alexandria, VA 22313-1450

Dear Sir:

Applicants submit information herewith to comply with the obligations set forth in 37 CFR §1.56. This submission is not an admission that any of the documents are prior art or otherwise relevant to the subject application.

This IDS is submitted:

- with a filed patent application or within 3 months of the US application filing date;
- before the mailing of a first office action on the merits;
- after the first office action, but prior to a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) or a certification set forth below; or
- after a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) and a certification set forth below, where this submission is a petition requesting consideration of this IDS.

If identified above, Applicant certifies that:

- the information was first cited in a communication from a foreign patent office in a counterpart foreign application less than 3 months prior to this IDS; or

] to the knowledge of the person signing this certification after making reasonable inquiry, the information was not known to any individuals designated in 37 CFR §1.56 more than 3 months prior to this IDS.

If any matters can be resolved by telephone, Applicant requests that the Patent and Trademark Office call the Applicant at the telephone number listed below.

Respectfully submitted,

By:



Daniel Hopen

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Talieh et al. Serial No.: 10/459,321 Filed: June 10, 2002 Title: Device Providing Electrical Contact To The Surface Of A Semiconductor Workpiece During Processing	Group Art Unit: Not yet assigned Examiner: Not yet assigned Docket: NT-105C5-US
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INFORMATION DISCLOSURE STATEMENT

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		6,537,144	Mar., 2003	Tsai et al.	Courtesy copy enclosed
		2002/0102853	Aug., 2002	Li	Courtesy copy enclosed
		6,270,646	Aug., 2001	Walton et al.	Courtesy copy enclosed
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		Robert D. Mikkola et al., "Investigation of the Roles of the Additive Components for Second Generation Copper Electroplating Chemistries Used for Advanced Interconnect Metalization", 2000 IEEE, IEEE Electron Devices Society, Pages 117-119, June 2000		In related S/N 09/685,934
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Examiner Signature		Date Considered	
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